

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
100V	4.2mΩ@10V	130A



合肥矽普半导体

Siliup Semiconductor Technology Co., Ltd

技术 品质 服务

www.siliup.com

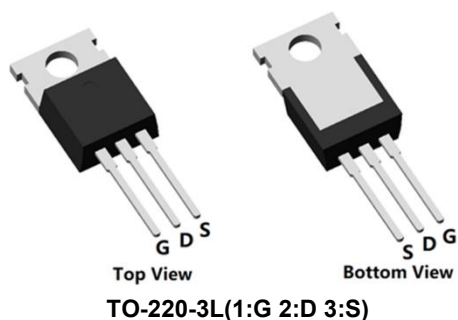
Feature

- Fast Switching
- Low Gate Charge and Rdson
- Advanced Split Gate Trench Technology
- 100% Single Pulse avalanche energy Test

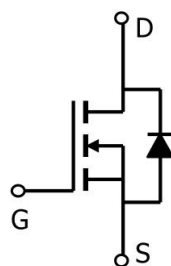
Applications

- Power switching application
- DC-DC Converter
- Power Management

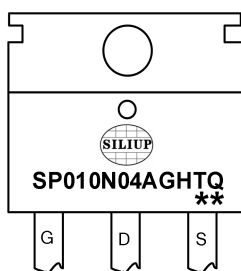
Package



Circuit diagram



Marking



SP010N04AGHTQ : Product code
** : Week code

Order Information

Device	Package	Unit/Tube
SP010N04AGHTQ	TO-220-3L	50

Absolute maximum ratings (Ta=25°C, unless otherwise noted)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	100	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current (Tc=25°C)	I_D	130	A
Continuous Drain Current (Tc=100°C)	I_D	87	A
Pulsed Drain Current	I_{DM}	520	A
Single Pulse Avalanche Energy ¹	E_{AS}	841	mJ
Power Dissipation (Tc=25°C)	P_D	180	W
Power Dissipation (Tc=100°C)	P_D	72	W
Thermal Resistance Junction-to-Case	$R_{\theta JC}$	0.69	°C/W
Storage Temperature Range	T_{STG}	-55 to 150	°C
Operating Junction Temperature Range	T_J	-55 to 150	°C

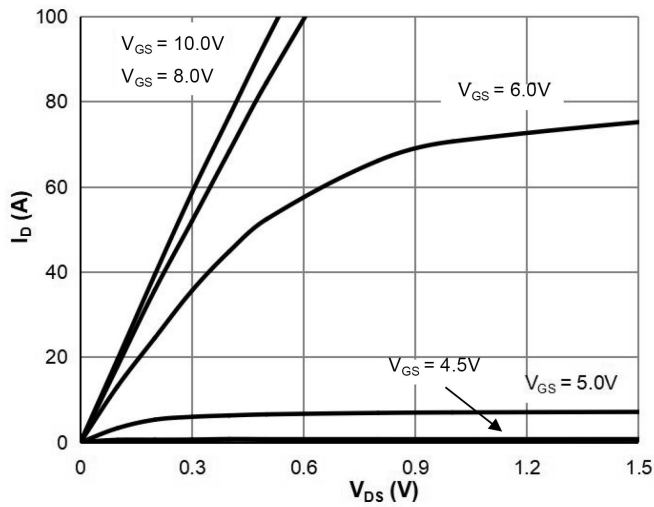
Electrical characteristics (Ta=25°C, unless otherwise noted)

Characteristics	Symbol	Test Condition	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	VGS=0V , ID=250uA	100	-	-	V
Drain Cut-Off Current	IDSS	VDS=80V , VGS=0V , TJ=25℃	-	-	1	uA
Gate Leakage Current	IGSS	VGS=±20V , VDS=0V	-	-	±100	nA
Gate Threshold Voltage	VGS(th)	VGS=VDS , ID =250uA	2.6	3.0	3.4	V
Drain-Source ON Resistance	RDS(ON)	VGS=10V , ID=30A	-	4.2	5.3	mΩ
Gate Resistance	RG	VDS=50V , VGS=0V , f=1MHz	-	2.8	-	Ω
Dynamic Characteristics						
Input Capacitance	Ciss	VDS=50V , VGS=0V , f=1.0MHz	-	4251	-	pF
Output Capacitance	Coss		-	692	-	
Reverse Transfer Capacitance	Crss		-	26	-	
Total Gate Charge	Qg	VDS=50V , VGS=10V , ID=20A	-	69	-	nC
Gate-Source Charge	Qgs		-	24	-	
Gate-Drain Charge	Qgd		-	18	-	
Gate Plateau Voltage	Vplateau		-	5.6	-	V
Switching Characteristics						
Turn-On Delay Time	td(on)	VGS=10V , VDS=50V , RL=2.5Ω , RG=3.0Ω	-	12	-	nS
Rise Time	tr		-	23	-	
Turn-Off Delay Time	td(off)		-	37	-	
Fall Time	tf		-	16	-	
Drain-Source Body Diode Characteristics						
Source-Drain Diode Forward Voltage	VSD	VGS=0V , IS=1A , TJ=25℃	-	-	1.2	V
Maximum Body-Diode Continuous Current	Is		-	-	130	A
Reverse Recovery Time	Trr	IS=20A, di/dt=100A/us, TJ=25℃	-	65	-	nS
Reverse Recovery Charge	Qrr		-	126	-	nC

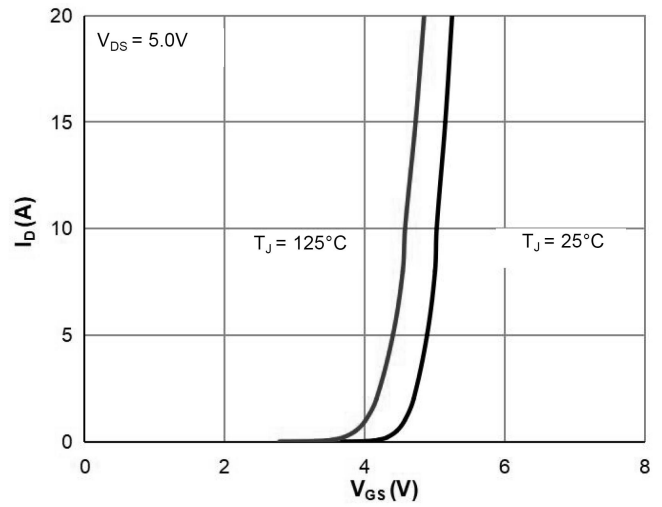
Note:

- The EAS test condition is $V_{DD}=50V, V_{GS}=10V, L=0.5mH, R_G=25\Omega$

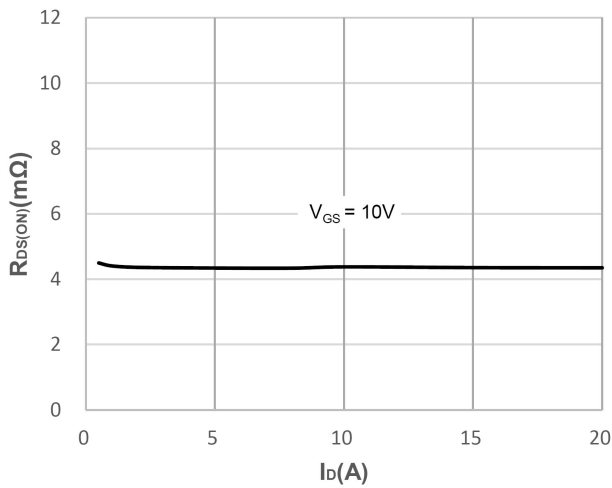
Typical Characteristics



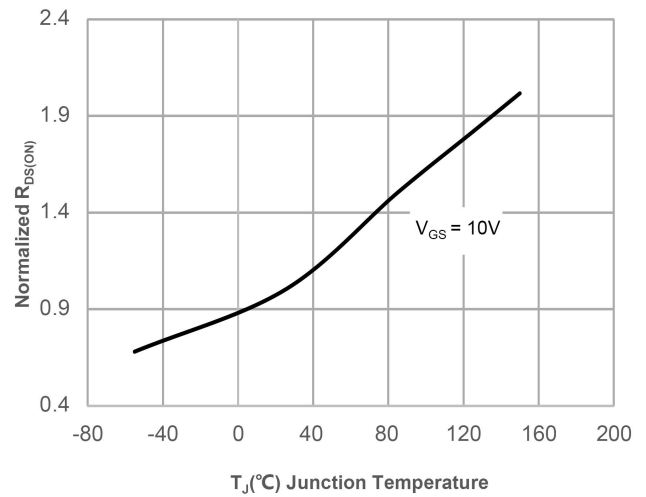
Typical Output Characteristics



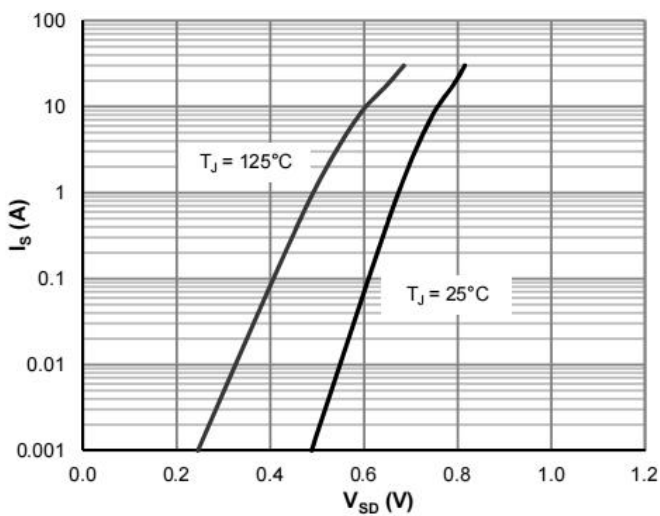
Transfer Characteristics



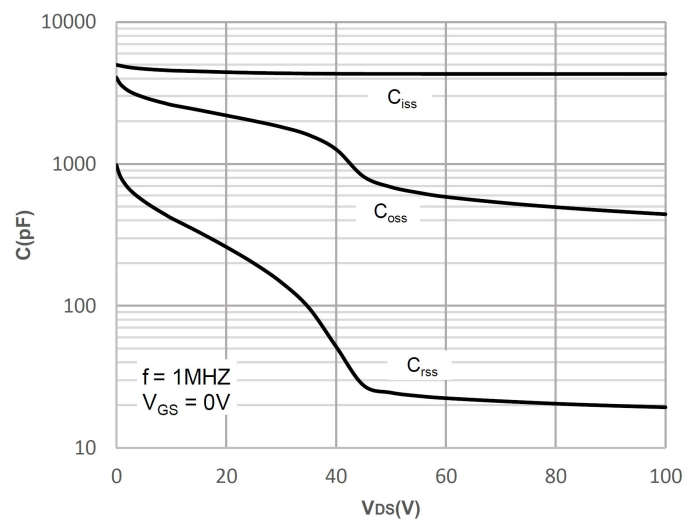
On-Resistance vs. Drain Current



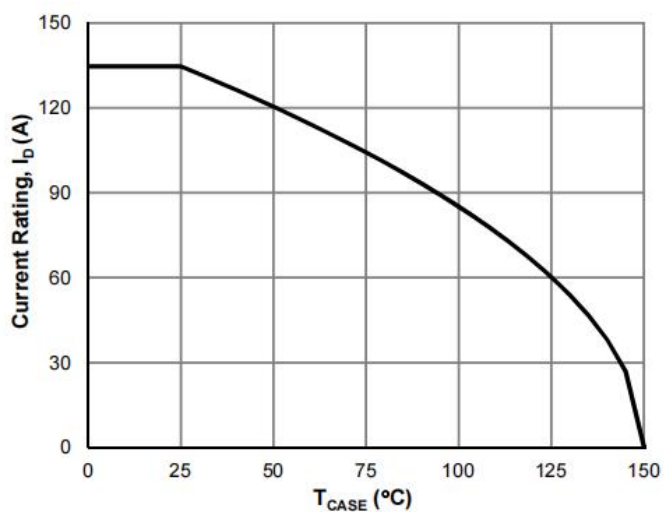
On-Resistance vs. Junction Temperature



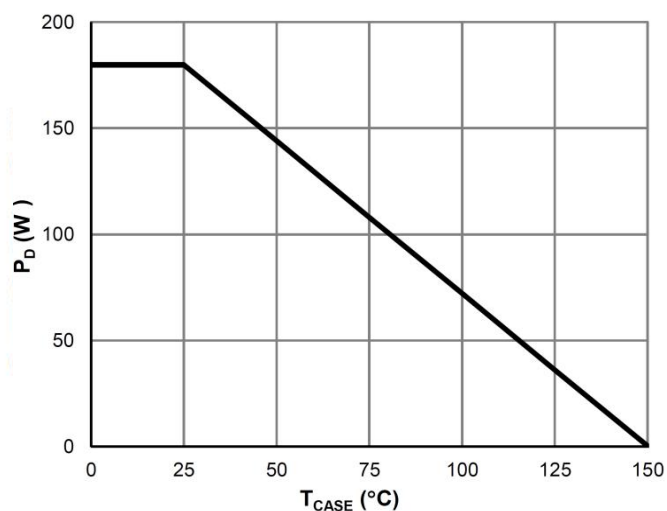
Body-Diode Characteristics



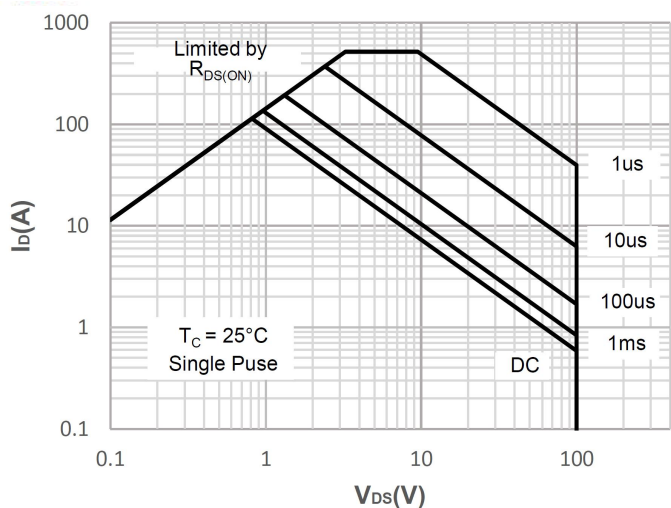
Capacitance Characteristics



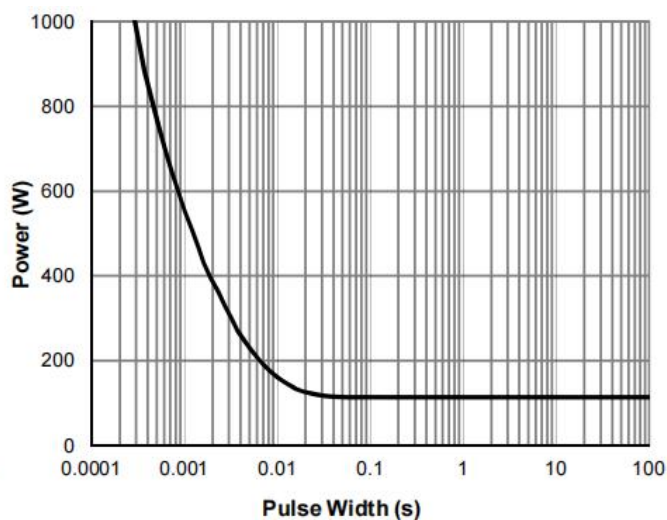
Current De-rating



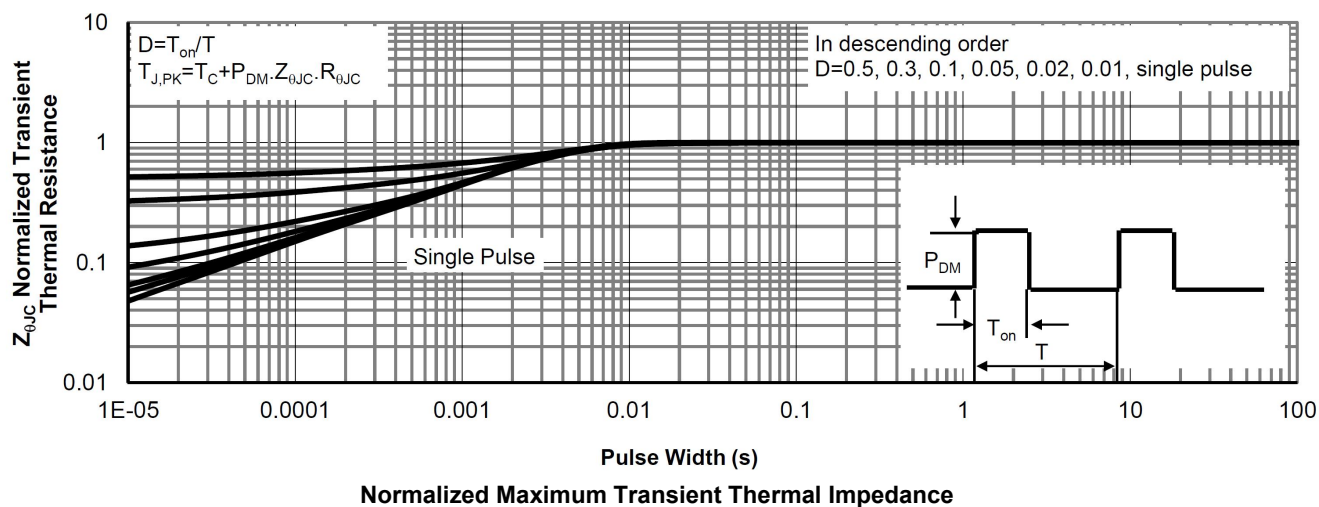
Power De-rating



Maximum Safe Operating Area



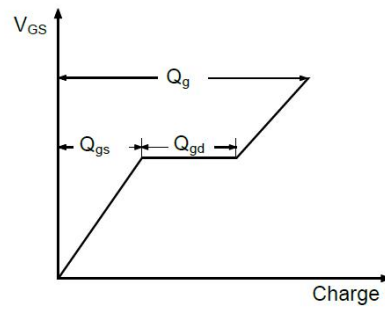
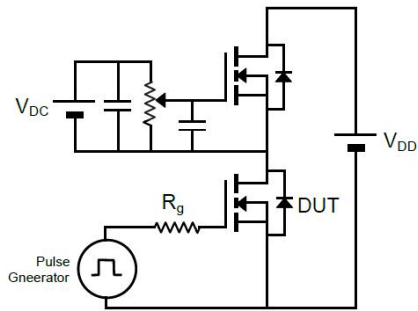
Single Pulse Power Rating, Junction-to-Case



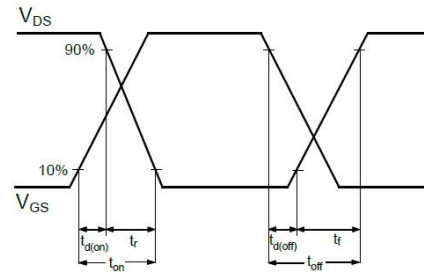
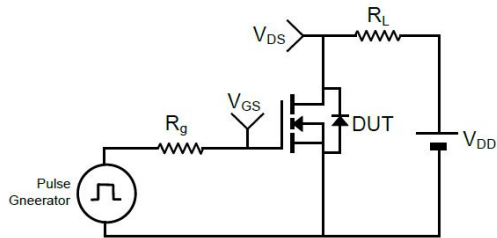
Normalized Maximum Transient Thermal Impedance

Test Circuit

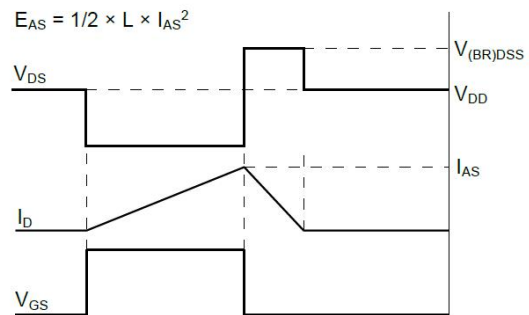
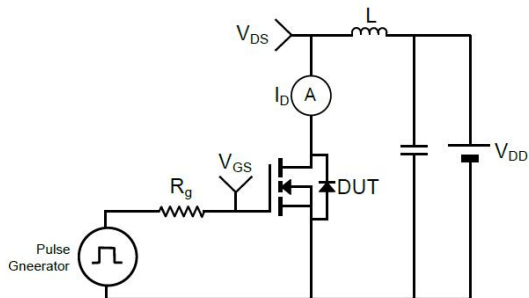
Gate Charge



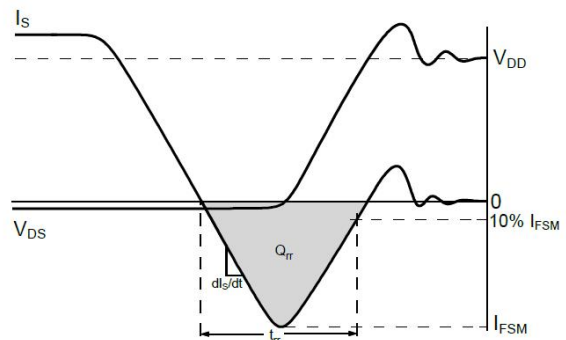
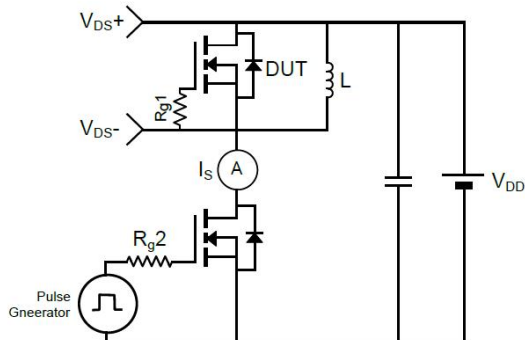
Resistive Load Switching Time



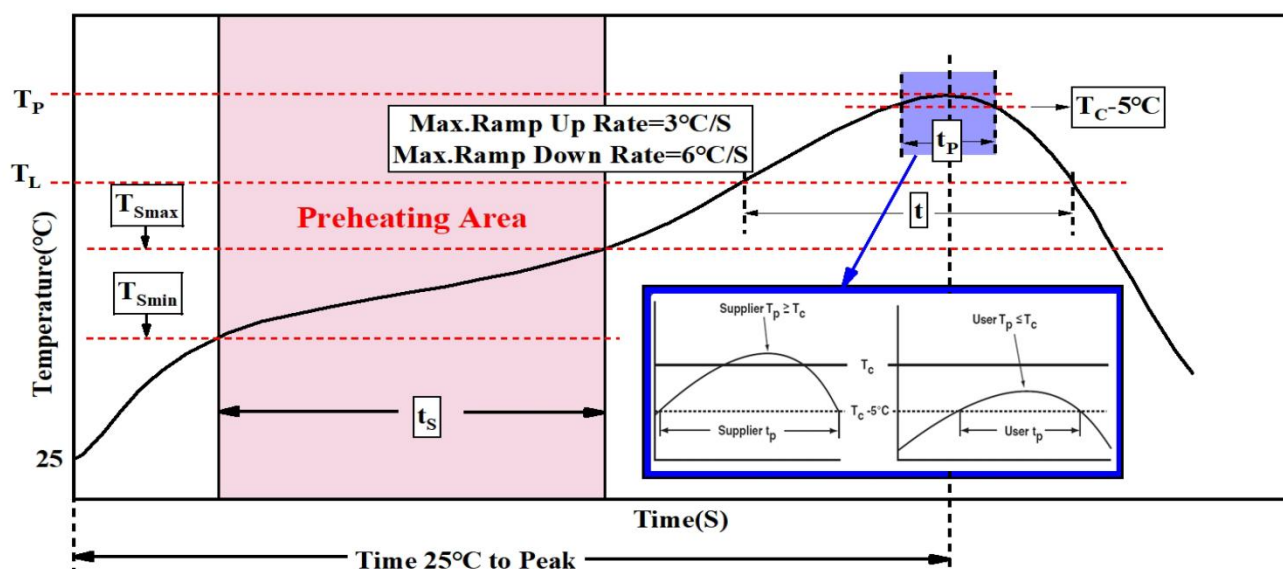
Un-clamped Inductive Load Switching



Drain-Source Body Diode Reverse Recovery



Temperature Profile for IR Reflow Soldering



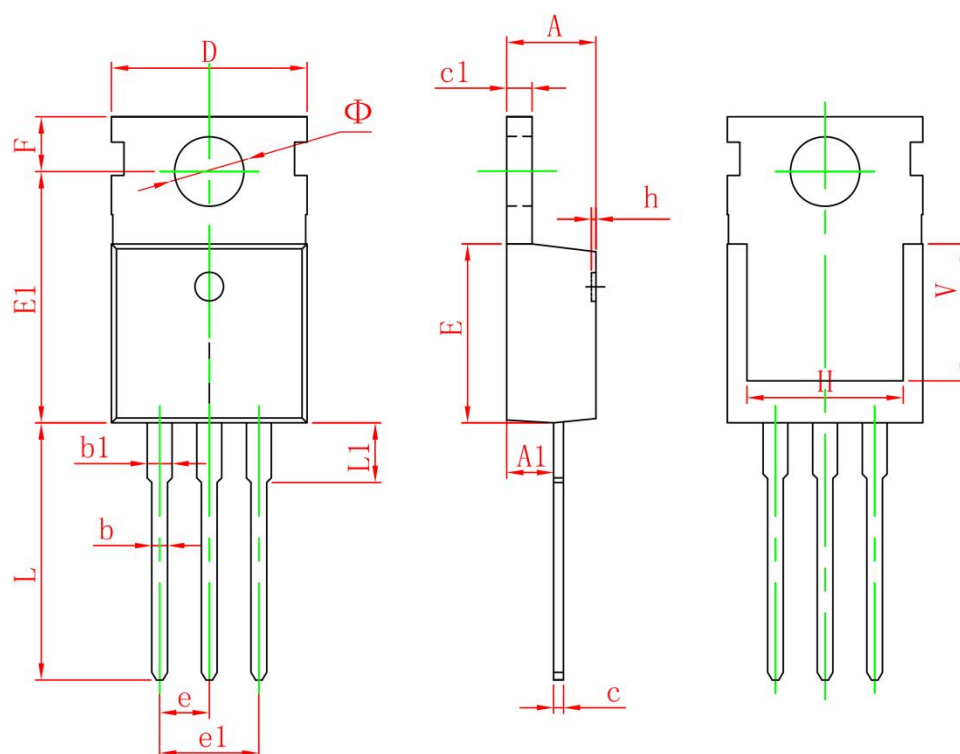
Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Preheat & Soak		
Temperature min (T_{Smin})	100°C	150°C
Temperature max (T_{Smax})	150°C	200°C
Time (T_{Smin} to T_{Smax}) (t_s)	60-120 seconds	60-120 seconds
Average ramp-up rate (T_{Smax} to T_P)	3 °C/second max.	3°C/second max.
Liquidous temperature (T_L)	183 °C	217°C
Time at liquidous (t_L)	60-150 seconds	60-150 seconds
Peak package body Temperature e (T_P)*	See Classification Temp in table 1	See Classification Temp in table 2
Time (t_P)** within 5°C of the specified classification temperature (T_C)	20** seconds	30** seconds
Average ramp-down rate (T_P to T_{Smax})	6 °C/second max.	6 °C/second max.
Time 25°C to peak temperature	6 minutes max.	8 minutes max.
* Tolerance for peak profile Temperature (T_P) is defined as a supplier minimum and a user maximum. ** Tolerance for time at peak profile temperature (t_P) is defined as a supplier minimum and a user maximum		

Table 1. SnPb Eutectic Process – Classification Temperatures (T_C)

Package Thickness	Volume mm ³ <350	Volume mm ³ ≥350
<2.5 mm	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2. Pb-free Process – Classification Temperatures (T_C)

Package Thickness	Volume mm ³ <350	Volume mm ³ 350-2000	Volume mm ³ >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 mm – 2.5 mm	260 °C	250 °C	245 °C
≥2.5 mm	250 °C	245 °C	245 °C

TO-220-3L Package Information


Symbol	Dimensions In Millimeters	
	Min.	Max.
A	4.300	4.700
A1	2.200	2.500
b	0.700	0.900
b1	1.100	1.400
c	0.300	0.700
c1	1.200	1.400
D	9.800	10.200
E	9.000	9.400
E1	12.700	13.500
e	2.490	2.590
e1	4.980	5.180
F	2.650	2.950
H	7.600	8.400
h	0.000	0.300
L	12.700	13.500
L1	2.850	3.250
V	6.900 REF.	
Φ	3.400	3.800